

SEMICONDUCTOR STRUCTURE AND METHOD FOR MANUFACTURING SEMICONDUCTOR STRUCTURE

ABSTRACT

The embodiments of the disclosure relate to the field of semiconductors, and provide a semiconductor structure and a method for manufacturing a semiconductor structure. The semiconductor structure includes: a substrate; a plurality of active layers arranged on the substrate and spaced apart from each other; and a plurality of bit lines, spaced apart from each other in a first direction and extending in a second direction. A first portion of each bit line covers side surfaces of respective active layers of the plurality of active layers, and a second portion of each bit line is located in the respective active layers. The first direction and the second direction are parallel to a surface of the substrate, and the first direction intersects with the second direction. Therefore, the reliability of the semiconductor structure may be improved.

[Fig. 2]